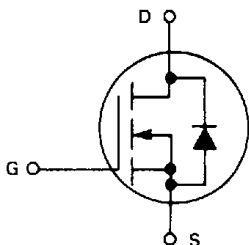
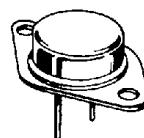


MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA
MTM55N10
MTM60N06
Designer's Data Sheet
**N-CHANNEL ENHANCEMENT-MODE SILICON GATE
 TMOS POWER FIELD EFFECT TRANSISTOR**

These TMOS Power FETs are designed for low voltage, high speed power switching applications such as switching regulators, converters, solenoid and relay drivers.

- Silicon Gate for Fast Switching Speeds — Switching Times Specified at 100°C
- Designer's Data — I_{DSS} , $V_{DS(on)}$, $V_{GS(th)}$ and SOA Specified at Elevated Temperature
- Rugged — SOA is Power Dissipation Limited
- Source-to-Drain Diode Characterized for Use With Inductive Loads


55 and 60 AMPERE
**N-CHANNEL TMOS
 POWER FETs**
 $R_{DS(on)} = 0.04 \text{ OHM}$
 100 VOLTS

 $R_{DS(on)} = 0.028 \text{ OHM}$
 60 VOLTS

**CASE 197A-03
 (TO-204AE)**

3

MAXIMUM RATINGS

Rating	Symbol	MTM		Unit
		60N06	55N10	
Drain-Source Voltage	V_{DSS}	60	100	Vdc
Drain-Gate Voltage ($R_{GS} = 1 \text{ M}\Omega$)	V_{DGR}	60	100	Vdc
Gate-Source Voltage Continuous Non-repetitive ($t_p \leq 50 \mu s$)	V_{GS} V_{GSM}	± 20 ± 40		Vdc Vpk
Drain Current Continuous Pulsed	I_D I_{DM}	60 300	55 275	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	250 2		Watts W/°C
Operating and Storage Temperature Range	T_J, T_{stg}	-65 to 150		°C

THERMAL CHARACTERISTICS

Thermal Resistance Junction to Case	$R_{\theta JC}$	0.5	°C/W
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	T_L	300	°C

Designer's Data for "Worst Case" Conditions

The Designer's Data Sheet permits the design of most circuits entirely from the information presented. Limit data — representing device characteristics boundaries — are given to facilitate "worst case" design.

MTM55N10/MTM60N06

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Drain-Source Breakdown Voltage ($V_{GS} = 0$, $I_D = 5.0$ mA)	MTM60N06 MTM55N10	$V_{(BR)DSS}$	60 100	— —	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = \text{Rated } V_{DS}$, $V_{GS} = 0$) $T_C = 125^\circ\text{C}$		I_{DSS}	— —	10 100	μAdc
Gate-Body Leakage Current ($V_{GS} = 20$ Vdc, $V_{DS} = 0$)		I_{GSS}	—	100	nAdc

ON CHARACTERISTICS*

Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 1$ mA), $V_{DS} = V_{GS}$ $T_J = 100^\circ\text{C}$		$V_{GS(th)}$	2 1.5	4.5 4	Vdc
Static Drain-Source On-Resistance ($V_{GS} = 10$ Vdc, $I_D = 30$ Adc) ($V_{GS} = 10$ Vdc, $I_D = 27.5$ Adc)	MTM60N06 MTM55N10	$R_{DS(on)}$	— —	0.028 0.04	Ohm
Drain-Source On-Voltage ($V_{GS} = 10$ V) ($I_D = 60$ Adc) ($I_D = 30$ Adc, $T_J = 100^\circ\text{C}$) ($I_D = 55$ Adc) ($I_D = 27.5$ Adc, $T_C = 100^\circ\text{C}$)	MTM60N06 MTM60N06 MTM55N10 MTM55N10	$V_{DS(on)}$	— — — —	1.98 1.68 2.6 2.2	Vdc
Forward Transconductance ($V_{DS} = 15$ V, $I_D = 30$ A) ($V_{DS} = 15$ V, $I_D = 27.5$ A)	MTM60N06 MTM55N10	g_{FS}	10 10	— —	mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	($V_{DS} = 25$ V, $V_{GS} = 0$, $f = 1$ MHz) See Figure 8	C_{iss}	—	5000	pF
Output Capacitance		C_{oss}	—	2500	
Reverse Transfer Capacitance		C_{rss}	—	1000	

SWITCHING CHARACTERISTICS* ($T_J = 100^\circ\text{C}$)

Turn-On Delay Time	($V_{DD} = 25$ V, $I_D = 0.5$ Rated I_D , $R_{gen} = 50$ ohms) See Figure 16	$t_{d(on)}$	—	70	ns
Rise Time		t_r	—	350	
Turn-Off Delay Time		$t_{d(off)}$	—	350	
Fall Time		t_f	—	400	
Total Gate Charge	$V_{DS} = 0.8$ Rated, $I_D = \text{Rated}$, $V_{GS} = 10$ V See Figure 15	Q_g	105 (Typ)	120	nC
		Q_{gs}	74 (Typ)	—	
		Q_{gd}	31 (Typ)	—	

SOURCE DRAIN DIODE CHARACTERISTICS*

Forward On-Voltage	($I_S = \text{Rated } I_D$, $V_{GS} = 0$)	V_{SD}	3.5	4	Vdc
Forward Turn-On Time		t_{on}	Limited by stray inductance		
Reverse Recovery Time		t_{rr}	200	—	ns

INTERNAL PACKAGE INDUCTANCE

Internal Drain Inductance (Measured from the contact screw on the header closer to the source pin and the center of the die)	L_d	5 (Typ)	—	nH
Internal Source Inductance (Measured from the source pin, 0.25" from the package to the source bond pad)	L_s	12.5 (Typ)	—	

*Pulse Test: Pulse Width ≤ 300 μs , Duty Cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS

MTM60N05, MTM60N06

FIGURE 1 — ON-REGION CHARACTERISTICS

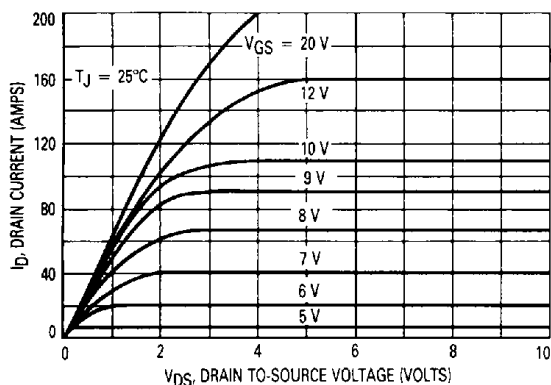


FIGURE 3 — TRANSFER CHARACTERISTICS

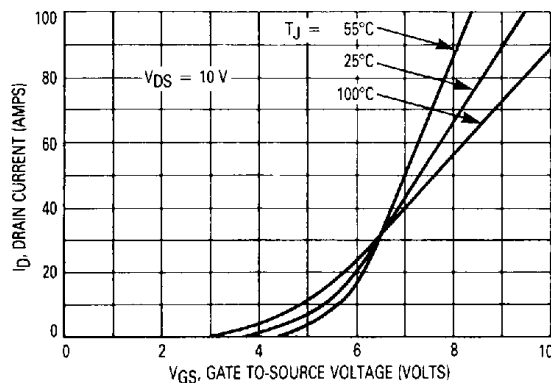
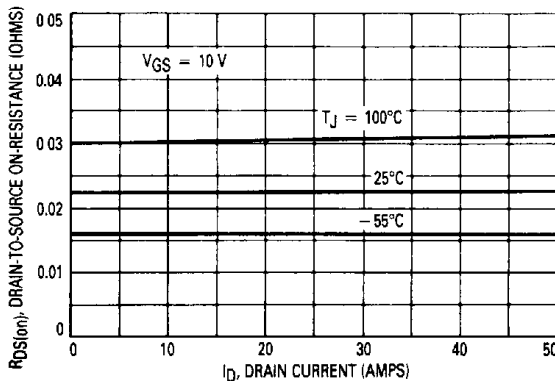


FIGURE 5 — ON-RESISTANCE versus DRAIN CURRENT



MTM55N08, MTM55N10

FIGURE 2 — ON-REGION CHARACTERISTICS

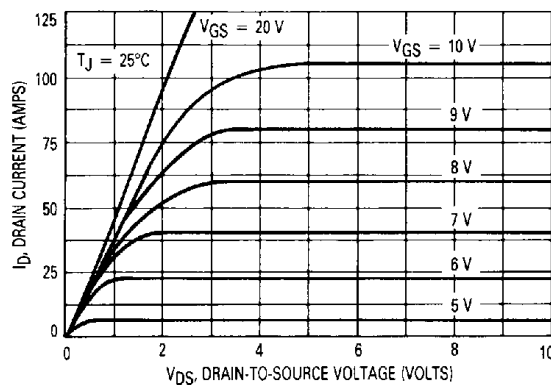


FIGURE 4 — TRANSFER CHARACTERISTICS

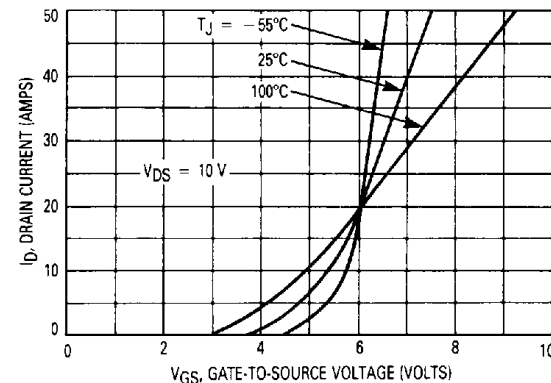
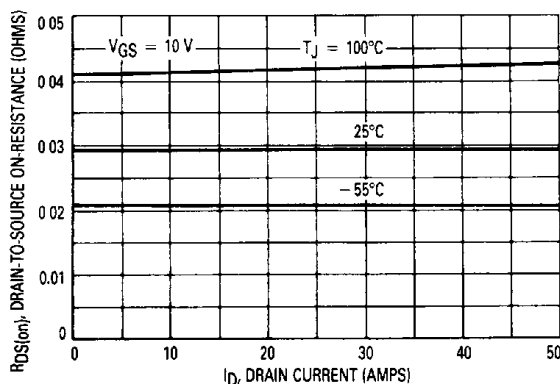


FIGURE 6 — ON-RESISTANCE versus DRAIN CURRENT



TYPICAL CHARACTERISTICS

FIGURE 7 — GATE-THRESHOLD VOLTAGE VARIATION WITH TEMPERATURE

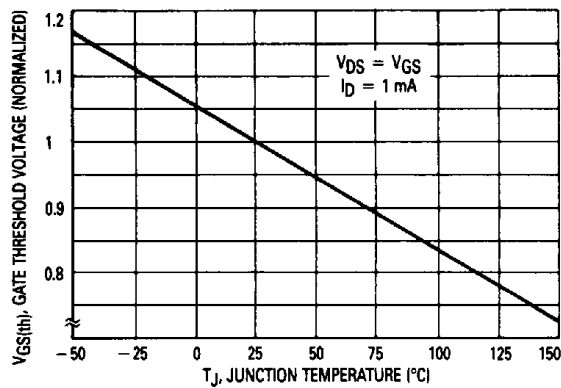


FIGURE 8 — CAPACITANCE VARIATION

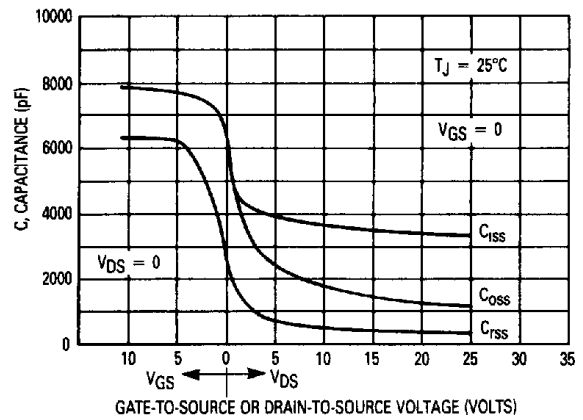


FIGURE 9 — BREAKDOWN VOLTAGE VARIATION WITH TEMPERATURE

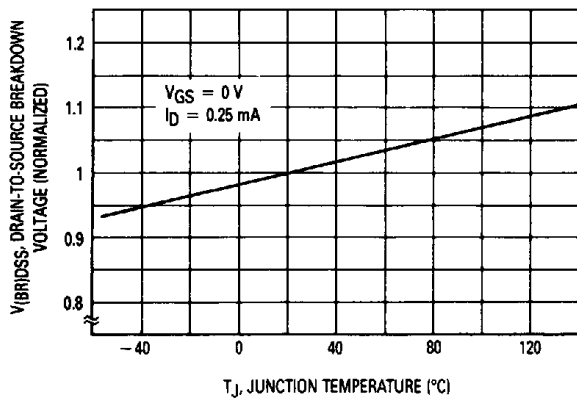


FIGURE 10 — ON-RESISTANCE VARIATION WITH TEMPERATURE

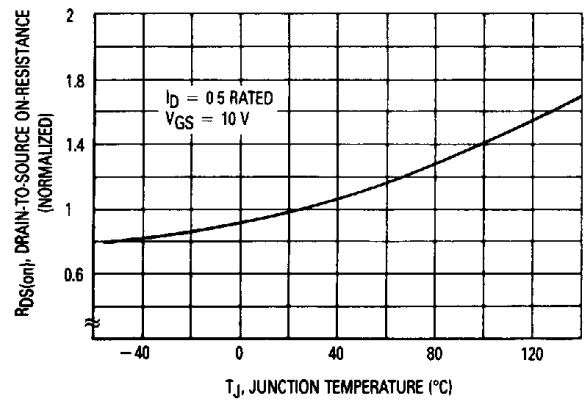
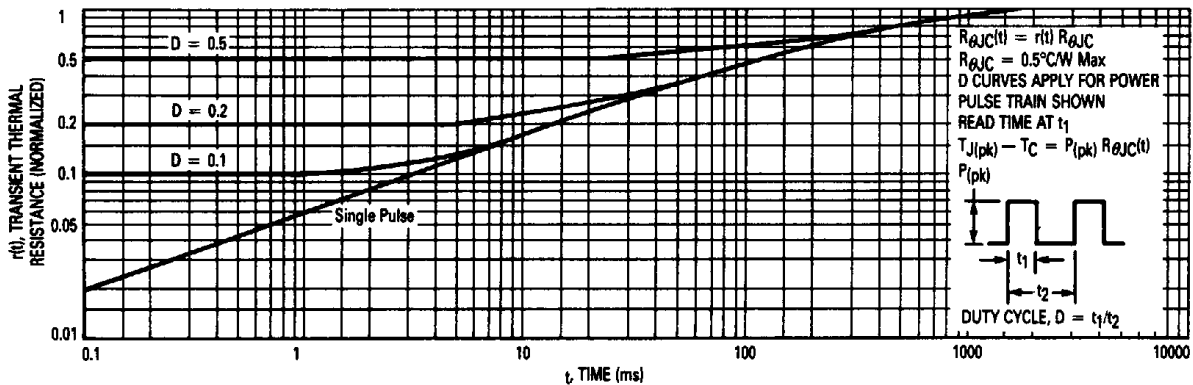


FIGURE 11 — THERMAL RESPONSE



SAFE OPERATING AREA INFORMATION

FIGURE 12 — MTM60N06

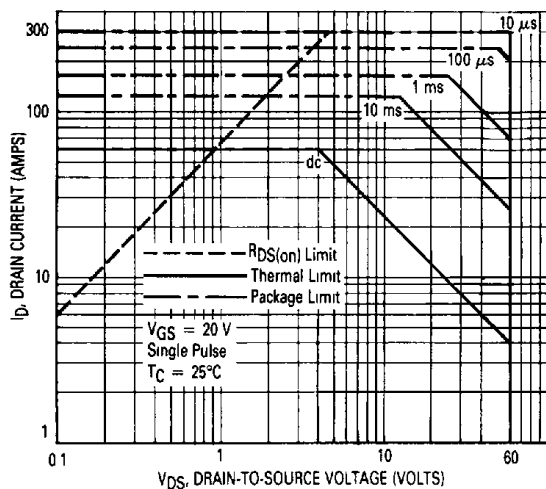
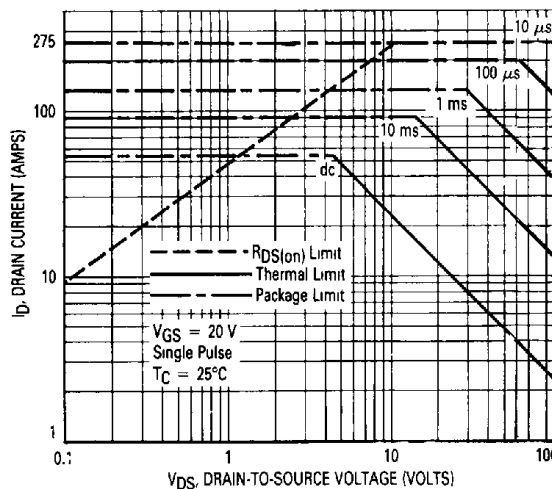


FIGURE 13 — MTM55N10



FORWARD BIASED SAFE OPERATING AREA

The FBSOA curves define the maximum drain-to-source voltage and drain current that a device can safely handle when it is forward biased, or when it is on, or being turned on. Because these curves include the limitations of simultaneous high voltage and high current, up to the rating of the device, they are especially useful to designers of linear systems. The curves are based on a case temperature of 25°C and a maximum junction temperature of 150°C. Limitations for repetitive pulses at various case temperatures can be determined by using the thermal response curves. Motorola Application Note, AN569, "Transient Thermal Resistance-General Data and Its Use" provides detailed instructions.

SWITCHING SAFE OPERATING AREA

The switching safe operating area (SOA) of Figure 14 is the boundary that the load line may traverse without incurring damage to the MOSFET. The fundamental limits are the peak current, I_{DM} and the breakdown voltage, $V_{(BR)DSS}$. The switching SOA shown in Figure 14 is applicable for both turn-on and turn-off of the devices for switching times less than one microsecond.

The power averaged over a complete switching cycle must be less than:

$$\frac{T_{J(max)} - T_C}{R_{\theta JC}}$$

FIGURE 14 — MAXIMUM RATED SWITCHING SAFE OPERATING AREA

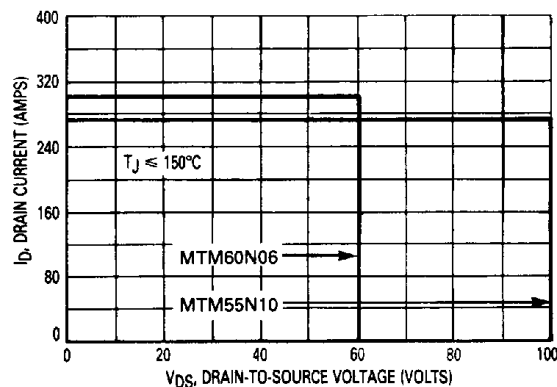


FIGURE 15 — STORED CHARGE versus GATE-TO-SOURCE VOLTAGE

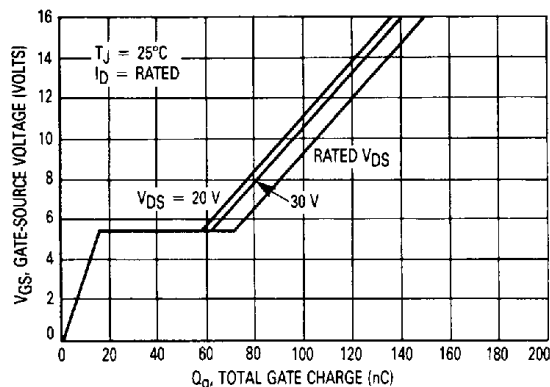


FIGURE 16 — RESISTIVE SWITCHING TIME VARIATION WITH GATE RESISTANCE

